IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:		
Shinji TADAKI, et al.))
		Group Art Unit: To be Assigned
Application No.: To be Ass	igned)
) Examiner: To be Assigned
Filed: March 23, 2001)
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For: PLASMA DISPLAT	Y PANEL AND PROCESS !	FOR MANUFACTURING ITS SUBSTRATE
STRUCTURE		

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

Before examination of the above-identified application, please amend the application as follows:

IN THE CLAIMS

Please AMEND the claims in accordance with the following:

[CLEAN VERSION NO BRACKETS AND UNDERLINING]

- 3. (ONCE AMENDED) A plasma display panel according to claim 1, wherein the filler is a silica powder.
 - 4. (ONCE AMENDED) A plasma display panel according to claim 1, wherein the

filler is an alumina powder.

- 5. (ONCE AMENDED) A plasma display panel according to claim 1, wherein the filler is hollow glass micro-balloons.
- 6. (ONCE AMENDED) A plasma display panel according to claim 1, wherein the thickness of the dielectric layer is 10 im or less.
- 13. (ONCE AMENDED) A plasma display panel according to claim 7 further comprising barrier ribs for partitioning a discharge space, wherein sidewalls of the barrier ribs are covered with the dielectric layer.
- 19. (ONCE AMENDED) A plasma display panel according to claim 7, wherein a light-shielding layer is provided on a front side with respect to a discharge space and the dielectric layer is provided on a rear side with respect to the light-shielding layer.
- 21. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by applying onto a substrate a low-melting-point glass paste in which a flake-form filler for enhancing reflectance is mixed, followed by burning.

- 25. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by applying onto a substrate a colloidal silica in which a flake-form filler for enhancing reflectance is mixed, followed by burning.
- 26. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by attaching to a supporting face a dielectric sheet in which a flake-form filler for enhancing reflectance is dispersed in a state such that the filler is uniformly oriented.
- 27. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by attaching and setting to a hollow form a dielectric sheet in which a flake-form filler for enhancing reflectance is dispersed in a state such that the filler is uniformly oriented, and then transferring the dielectric sheet to a substrate.

REMARKS

This Preliminary Amendment is submitted to improve the form of the specification as originally-filed and to delete the multiple dependent claims.

It is respectfully requested that this Preliminary Amendment be entered in the abovereferenced application.

Page 4

If any further fees are required in connection with the filing of this Preliminary Amendment, please charge same to our Deposit Account No. 19-3935.

Respectfully submitted,

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By:

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Date: March 26, 2001

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS

Please **AMEND** the following claims:

- 3. (ONCE AMENDED) A plasma display panel according to claim 1 [or claim 2], wherein the filler is a silica powder.
- 4. (ONCE AMENDED) A plasma display panel according to claim 1 [or claim 2], wherein the filler is an alumina powder.
- 5. (ONCE AMENDED) A plasma display panel according to claim 1 [or claim 2], wherein the filler is hollow glass micro-balloons.
- 6. (ONCE AMENDED) A plasma display panel according to [any one of claim 1 to claim 5]claim 1, wherein the thickness of the dielectric layer is 10 im or less.
- 13. (ONCE AMENDED) A plasma display panel according to claim 7 [or claim 8] further comprising barrier ribs for partitioning a discharge space, wherein sidewalls of the barrier ribs are covered with the dielectric layer.
- 19. (ONCE AMENDED) A plasma display panel according to claim 7 [or claim 8], wherein a light-shielding layer is provided on a front side with respect to a discharge space and the dielectric layer is provided on a rear side with respect to the light-shielding layer.

Page 6

- 21. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17 [or claim 20], the dielectric layer is formed by applying onto a substrate a low-melting-point glass paste in which a flake-form filler for enhancing reflectance is mixed, followed by burning.
- 25. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17 [or claim 20], the dielectric layer is formed by applying onto a substrate a colloidal silica in which a flake-form filler for enhancing reflectance is mixed, followed by burning.
- 26. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17 [or claim 20], the dielectric layer is formed by attaching to a supporting face a dielectric sheet in which a flake-form filler for enhancing reflectance is dispersed in a state such that the filler is uniformly oriented.
- 27. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17 [or claim 20], the dielectric layer is formed by attaching and setting to a hollow form a dielectric sheet in which a flake-form filler for enhancing reflectance is dispersed in a state such that the filler is uniformly oriented, and then transferring the dielectric sheet to a substrate.